

L Number	Hits	Search Text	DB	Time stamp
11	2	("6002147").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:40
12	2	("6298551").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:42
15	2	("5172301").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:45
16	2	("5920458").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:46
17	2	("5659458").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:46
18	2	("5467251").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:47
19	2	("5352926").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:50
20	2	("5468681").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:51
21	2	("6190941").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:52
22	2	("4509096").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 16:52
23	2	("5814535").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 17:14
24	347	pin with solder adj ball and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 17:32
25	765	akram.in. and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/07 17:34

-	2	stack adj chip and 257/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/05 11:05
-	20	("4551629" "4770640" "4868712" "4875139" "4943539" "4983533" "5019943" "5110298" "5202754" "5235672" "5247423" "5266833" "5270261" "5285571" "5315147" "5506450" "5517754" "5571754" "5585674" "5623166").PN.	USPAT	2002/11/05 11:01
-	8	("3859127" "5103287" "5104820" "5126231" "5196378" "5259925" "5266833" "5397916").PN.	USPAT	2002/11/05 11:04
-	6	stack adj chip and electrode and 257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/05 11:06
-	19	stack adj chip and electrode and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/05 11:08
-	4	stack adj chip and electrode and 361/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/05 11:10
-	3	stack adj chip and electrode and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/05 11:44
-	3185	257/758	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/05 12:36
-	1776	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/06 10:59
-	1728	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/06 13:57
-	1	"6472738"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/06 14:16
-	5	("5404581" "5614442" "5614743" "5635762" "6075712").PN.	USPAT	2002/11/06 13:57
-	206	hole and semiconductor adj chip and 257/686.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/06 18:05
-	2204	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 18:41

-	3	("6339237").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/06 19:19
-	2651	(257/391,392,331,282,280,295).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/07 16:34
-	1	"5293072".PN.	USPAT	2002/11/07 13:24